

Product Change Notification - KSRA-05XGMC821

Date:

14 Aug 2019

Product Category:

Ethernet Switches; Ethernet Controllers

Affected CPNs:

Notification subject:

CCB 3861 and 3861.001 Initial Notice: Qualification of ASE as a new assembly site for selected products available in 100L LFBGA (9x9x1.38mm and 10x10x1.42mm) packages.

Notification text:
PCN Status:

Initial notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:

Qualification of ASE as a new assembly site for selected products available in 100L LFBGA (9x9x1.38mm and 10x10x1.42mm) packages.

Pre Change:

Assembled at OSE assembly site using 2300 die attach, E770 molding compound materials and 25+/-10um solder mask thickness.

Post Change:

Assembled at ASE assembly site using 2100 die attach, KE-G1250NAS molding compound materials and 30 +/-10um solder mask thickness.

Pre and Post Change Summary:

		Pre Change	Post Change
Assembly Site		Orient Semiconductor Electronics, Ltd (OSE)	ASE Inc. (ASE)
Wire material		Au	Au
Die attach material		2300	2100
Molding compound material		E770	KE-G1250NAS
Substrate material	Core	HL832NX	HL832NX
	Solder Mask	AUS308	AUS308
	Solder Mask Thickness	25+/-10um	30+/-10 um
Solder Ball	100L LFBGA (10x10x1.42mm)	SAC405	SAC405



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	100L LFBGA (9x9x1.38mm)	SAC305	SAC305

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve on time delivery performance by qualifying ASE as a new assembly site

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

October 2019

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

Workweek	August 2019					-->	October 2019				
	31	32	33	34	35		40	41	42	43	44
Initial PCN Issue Date				X							
Qual Report Availability									X		
Final PCN Issue Date									X		

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:

August 14, 2019: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_KSRA-05XGMC821_Qual_Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN)

KSZ8841-16MBL

KSZ8841-16MBLI

KSZ8842-16MBL

KSZ8842-16MBLI

KSZ8842-16MBLI-TR

KSZ8893MBL

KSZ8893MBLI

KSZ8893MBL-TR